



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR POWERPAK® SO-8L					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
Bond int.	520	270 000	200 °C, N2	0	0.00
HAST	1394	155 800	130 °C, 85 % RH	0	0.00
Pressure pot	1886	236 160	121 °C, 15 PSIG	0	0.00
Temp. cycle	1968	2 501 000	-55 °C to +150 °C	0	0.00
Solderability	255	2 040	8 hours	0	0.00
Power cycle	1066	18 368 000	$\Delta T_J = 100$ °C	0	0.00
Solder dunk	1099	3 297	260 °C, 10 s	0	0.00